#### **Power MOSFET**

# -60 V, -2.6 A, Single P-Channel SOT-223

#### **Features**

- Design for low R<sub>DS(on)</sub>
- Withstands High Energy in Avalanche and Commutation Modes
- AEC-Q101 Qualified NVF2955
- These Devices are Pb-Free and are RoHS Compliant

#### **Applications**

- Power Supplies
- PWM Motor Control
- Converters
- Power Management

#### **MAXIMUM RATINGS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Parame	Symbol	Value	Unit		
Drain-to-Source Voltage			V <sub>DSS</sub>	-60	V
Gate-to-Source Voltage	Gate-to-Source Voltage			±20	V
Continuous Drain	Steady	T <sub>A</sub> = 25°C	I <sub>D</sub>	-2.6	Α
Current (Note 1)	State	T <sub>A</sub> = 85°C		-2.0	
Power Dissipation (Note 1)	Steady State	T <sub>A</sub> = 25°C	P <sub>D</sub>	2.3	W
Continuous Drain	Steady	T <sub>A</sub> = 25°C	I <sub>D</sub>	-1.7	Α
Current (Note 2)	State	T <sub>A</sub> = 85°C		-1.3	
Power Dissipation (Note 2)		T <sub>A</sub> = 25°C	P <sub>D</sub>	1.0	W
Pulsed Drain Current	I <sub>DM</sub>	-17	Α		
Operating Junction and St	T <sub>J</sub> , T <sub>STG</sub>	–55 to 175	°C		
Single Pulse Drain-to-Source Avalanche Energy ( $V_{DD}$ = 25 V, $V_{G}$ = 10 V, $I_{PK}$ = 6.7 A, L = 10 mH, $R_{G}$ = 25 $\Omega$ )			EAS	225	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)			TL	260	°C

#### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Tab (Drain) - Steady State (Note 2)	$R_{\theta JC}$	14	
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	65	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	150	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- When surface mounted to an FR4 board using 1 in. pad size (Cu. area = 1.127 in<sup>2</sup> [1 oz] including traces)
- When surface mounted to an FR4 board using the minimum recommended pad size (Cu. area = 0.341 in<sup>2</sup>)

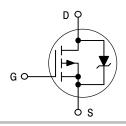


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V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> MAX
-60 V	145 mΩ @ –10 V	-2.6 A

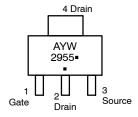
#### P-Channel



# MARKING DIAGRAM AND PIN ASSIGNMENT



SOT-223 CASE 318E STYLE 3



A = Assembly Location

/ = Year

W = Work Week

■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTF2955T1G	SOT-223 (Pb-Free)	1000 /Tape & Reel
NVF2955T1G	SOT-223 (Pb-Free)	1000/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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#### **ELECTRICAL CHARACTERISTICS** (T<sub>.I</sub>=25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>				66.4		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = -60 \text{ V}$	T <sub>J</sub> = 25°C			-1.0	μΑ
			T <sub>J</sub> = 125°C			-50	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V				±100	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$	I <sub>D</sub> = -1.0 mA	-2.0		-4.0	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -0.75 A		145	170	mΩ
		V <sub>GS</sub> = -10 \	/, I <sub>D</sub> = -1.5 A		150	180	
		V <sub>GS</sub> = -10 V, I <sub>D</sub> = -2.4 A			154	185	
Forward Transconductance	9 <sub>FS</sub>	V <sub>GS</sub> = -15 V, I <sub>D</sub> = -0.75 A			1.77		S
CHARGES AND CAPACITANCES							
Input Capacitance	C <sub>ISS</sub>	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 25 \text{ V}$			492		pF
Output Capacitance	Coss				165		
Reverse Transfer Capacitance	C <sub>RSS</sub>				50		
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = 10 \text{ V}, V_{DS} = 30 \text{ V},$ $I_{D} = 1.5 \text{ A}$			14.3		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>				1.2		-
Gate-to-Source Charge	Q <sub>GS</sub>				2.3		
Gate-to-Drain Charge	Q <sub>GD</sub>				5.2		
SWITCHING CHARACTERISTICS (Note 4)							
Turn-On Delay Time	t <sub>d(ON)</sub>	V <sub>GS</sub> = 10 V,	V <sub>DD</sub> = 25 V,		11		ns
Rise Time	t <sub>r</sub>	I <sub>D</sub> = 1.5 A, R <sub>L</sub> =	$R_G = 9.1 \Omega$ 25 $\Omega$		7.6		
Turn-Off Delay Time	t <sub>d(OFF)</sub>	_			65		
Fall Time	t <sub>f</sub>				38		
DRAIN-SOURCE DIODE CHARACTERIST	ics						
Forward Diode Voltage	V <sub>SD</sub>	$V_{GS} = 0 \text{ V},$ $I_{S} = 1.5 \text{ A}$	T <sub>J</sub> = 25°C		-1.10	-1.30	V
			T <sub>J</sub> = 125°C		-0.9		1
Reverse Recovery Time	t <sub>RR</sub>		<u> </u>		36		
Charge Time	ta	$V_{GS} = 0 \text{ V}, \text{ dI}_{S}/\text{dt} = 100 \text{ A}/\mu\text{s},$ $I_{S} = 1.5 \text{ A}$			20		ns
Discharge Time	t <sub>b</sub>				16		
Reverse Recovery Charge	Q <sub>RR</sub>				0.139	<b> </b>	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width ≤ 300µs, duty cycle ≤ 2%.

4. Switching characteristics are independent of operating junction temperatures.

#### TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)

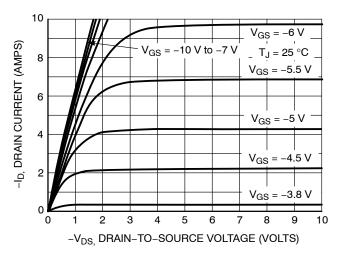


Figure 1. On-Region Characteristics

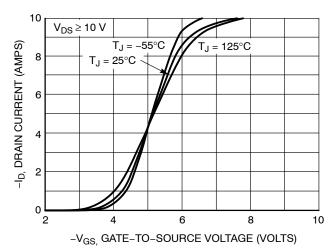


Figure 2. Transfer Characteristics

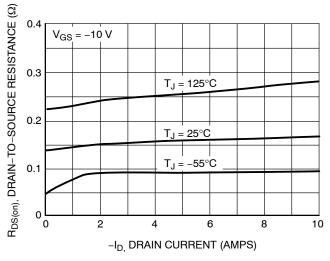


Figure 3. On-Resistance versus Drain Current and Temperature

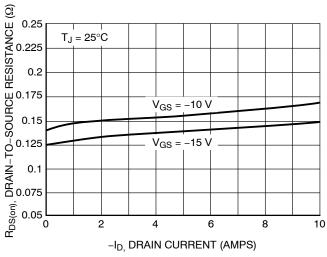
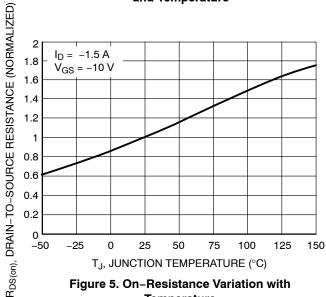


Figure 4. On-Resistance versus Drain Current and Gate Voltage



**Temperature** 

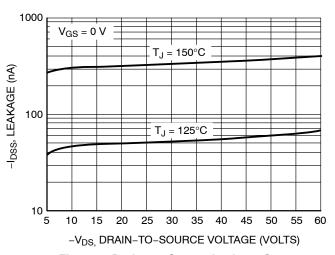
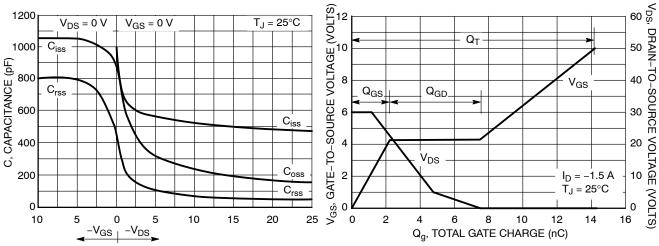


Figure 6. Drain-to-Source Leakage Current versus Voltage

#### TYPICAL PERFORMANCE CURVES (T<sub>.J</sub> = 25°C unless otherwise noted)



GATE-TO-SOURCE OR DRAIN-TO-SOURCE VOLTAGE (VOLTS)

Figure 7. Capacitance Variation

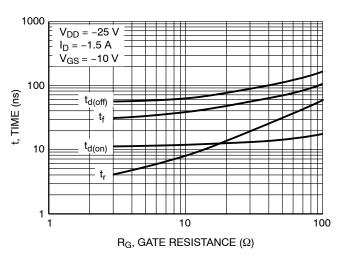


Figure 9. Resistive Switching Time Variation versus Gate Resistance

Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

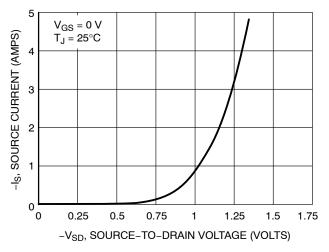


Figure 10. Diode Forward Voltage versus Current

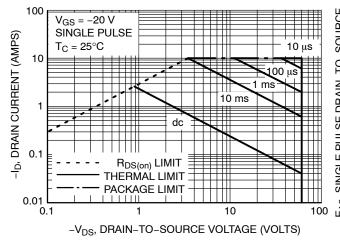


Figure 11. Maximum Rated Forward Biased Safe Operating Area

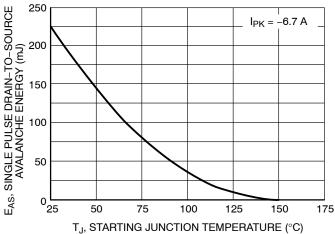


Figure 12. Maximum Avalanche Energy versus Starting Junction Temperature

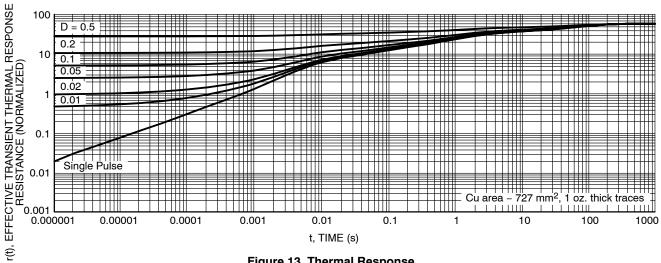
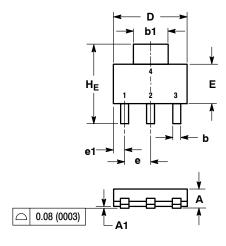
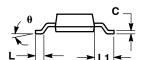


Figure 13. Thermal Response

#### PACKAGE DIMENSIONS

#### SOT-223 (TO-261) CASE 318E-04 ISSUE N



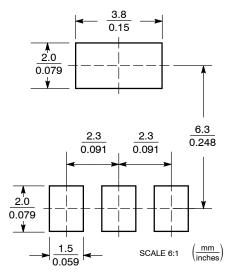


- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.50	1.63	1.75	0.060	0.064	0.068	
A1	0.02	0.06	0.10	0.001	0.002	0.004	
b	0.60	0.75	0.89	0.024	0.030	0.035	
b1	2.90	3.06	3.20	0.115	0.121	0.126	
С	0.24	0.29	0.35	0.009	0.012	0.014	
D	6.30	6.50	6.70	0.249	0.256	0.263	
E	3.30	3.50	3.70	0.130	0.138	0.145	
е	2.20	2.30	2.40	0.087	0.091	0.094	
e1	0.85	0.94	1.05	0.033	0.037	0.041	
٦	0.20			0.008	-		
L1	1.50	1.75	2.00	0.060	0.069	0.078	
HE	6.70	7.00	7.30	0.264	0.276	0.287	
θ	0°	_	10°	0°	_	10°	

- PIN 1. GATE 2. DRAIN
  - SOURCE

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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# Partnership :

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